Closing the Loop: Advancing Circularity in Semiconductor Chips and Chip-integrated Components

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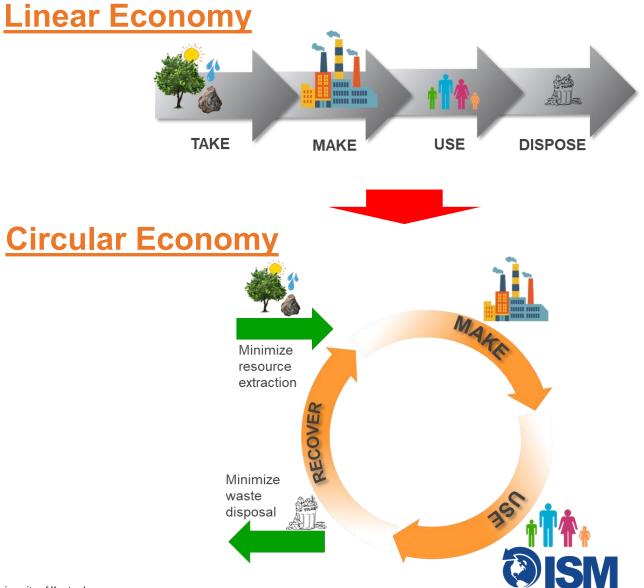
Introduction: Circular Economy

• Transition from the linear take-makeuse-dispose approach to an economy with restorative and regenerative flows

- Circular Economy (CE) Principles¹:
 - Eliminate waste and pollution
 - Circulate materials and products at the highest value
 - Regenerate nature and preserve natural capital

1) Ellen MacArthur Foundation. Towards the Circular Economy Vol. 1: an economic and business rationale for an accelerated transition. Ellen McArthur. 2013.

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Defining Circular Economy (CE)

Circular Economy is an

- Economic system
- That uses a systemic approach to maintain a *circular flow of resources*
- By recovering, retaining or adding to their *value*
- While contributing to *sustainable development*

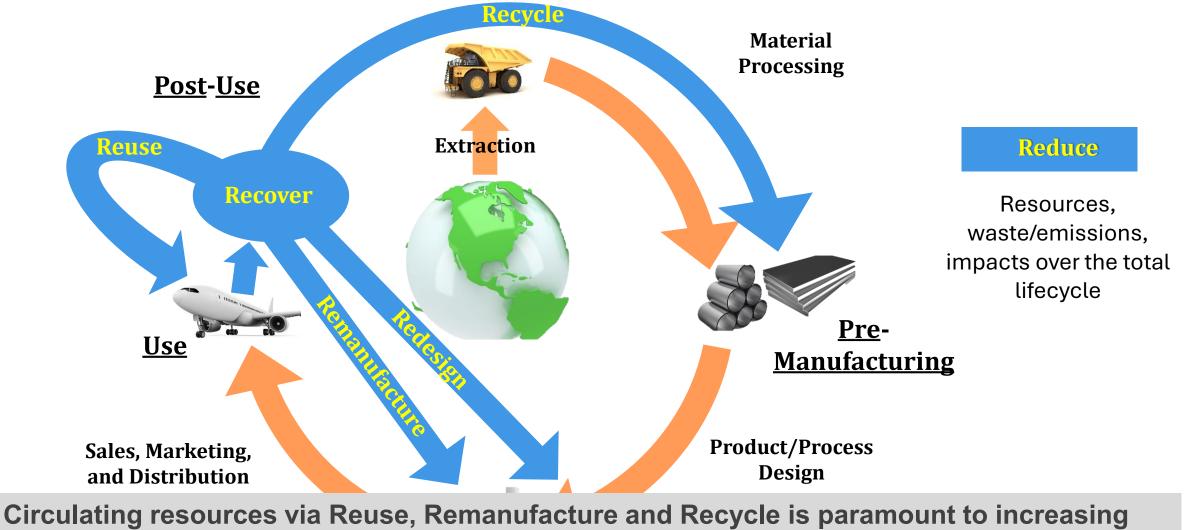
ISO	International Standard
	ISO 59004
Circular economy — Vocabulary, principles and guidance for implementation Economie circulare — Vocabulare, principes et recommandations pour la mise en œuvre	First edition 2024-05
Reference number ISO 59004-2024(en)	© ISO 2024



Based on ISO 59004



Closing the Loop: Value Recovery at End-of-Life (EoL)



supply chain resilience amid tariffs and trade wars

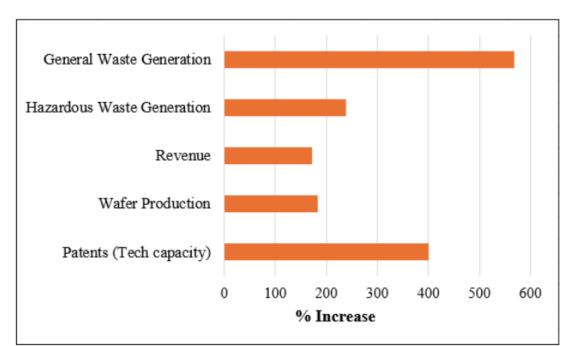


Manufacturing



Semiconductor Manufacturing Sector Status

- High energy consumption, water use and rare/critical materials¹
- High GHG emissions, pollution and health hazards²
- Significant technological advances in design and manufacturing
- However, improvements in waste generation, resource use and impacts not comparable³
- Proliferating semiconductor chip use across all sectors⁴



Semiconductor Foundry Performance⁵: Variation from 2012 - 2021

1) Hsieh et al., 2023, Harrington et al., 2022, Gatto and Nuta, 2024;2) Harrington et al., 2022; Ruberti, 2023, Nagapurkar et al., 2024; 3) Rubert et al., 2024, Garcia Bardon et al., 2020; 4) Burkacky et al., 2022; 5) Based on Ruberti et al., 2024.



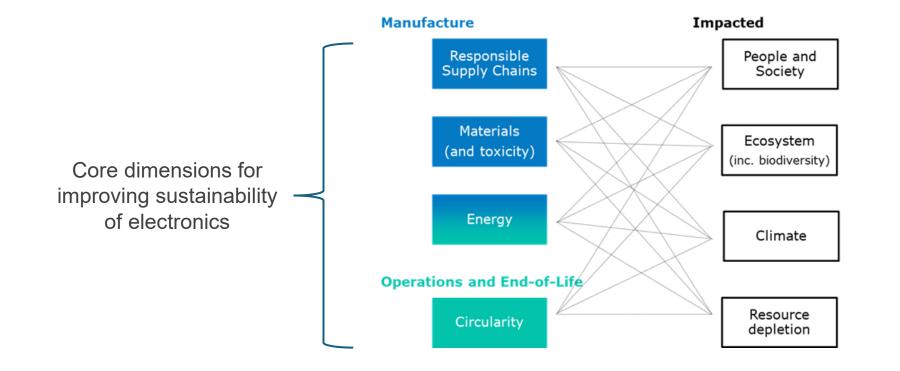


Sustainability in Electronics Sector

- INEMI Sustainable Electronics Roadmap¹
 - Call for sustainable practices and Circular Economy initiatives in electronics



International Electronics Manufacturing Initiative



1) Okrasinski, et al. (2023).

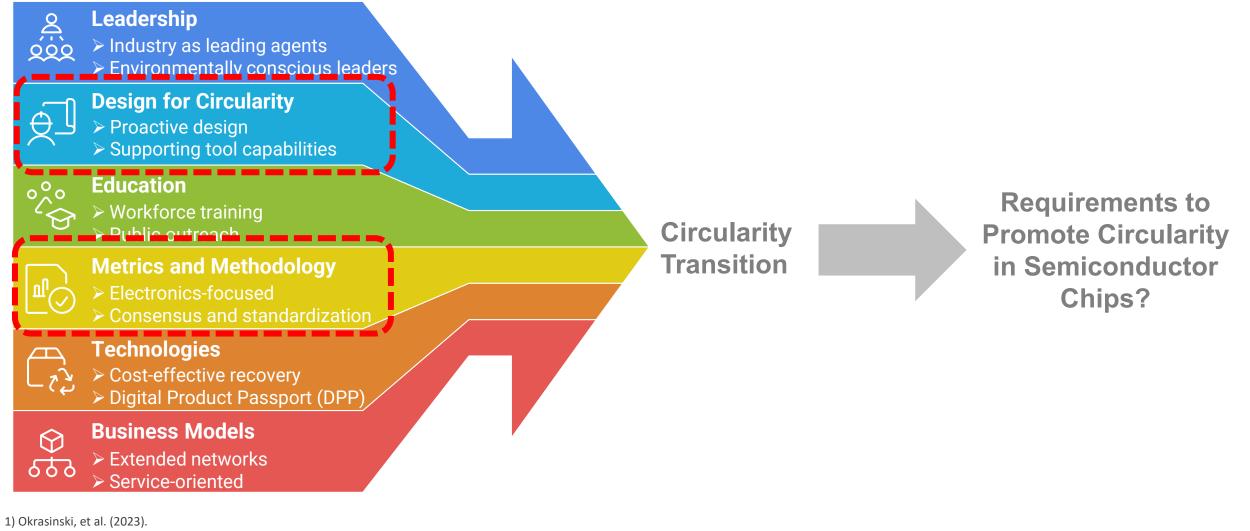




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Interdependent Impacts of the Electronics Life Cycle¹

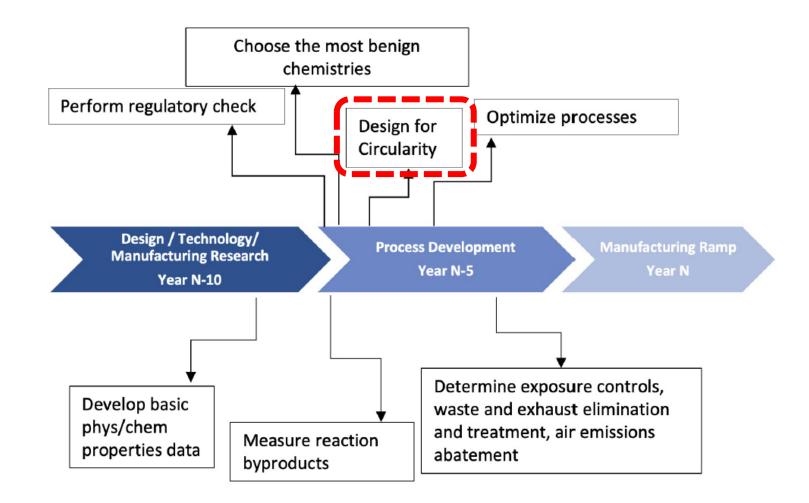
INEMI Roadmap: Electronics Industry Issues/Needs





Microelectronics & Advanced Packaging Technologies Roadmap (MAPT)

- Semiconductor Research
 Corporation's (SRC) 2030
 Decadal Plan¹
- Aims to guide semiconductor industry toward sustainable innovation
- Focus on energy, environmental, and workforce sustainability





1) SRC-MAPT. (2023).

SRC-MAPT Roadmap – Focus Areas

Energy Sustainability		
Chip Design	System in Package	
for Energy	(SiPs): Integrating	

 Transition from 2D to 3D Semiconductor Technologies

□ AI & ML Integration

Environment Sustainability

Sustainable Manufacturing

Efficiency

Distributed Energy Resources

Multiple Chips

Integrating Environmental Metrics

Circular Economy Pathways

Workforce Sustainability

Academia, Industry & Government Collaboration Enhance Skills in technological sector Multidisciplinary teams

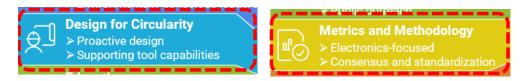
1) Based on SRC-MAPT. (2023).





Circular Product Design: Assessment & Improvement

- Industry-engaged efforts for circular product design and assessment
 - Project 1: Metrics-based System for <u>Evaluating Product Circularity</u> and Enhancing the <u>Circular Design of Consumer Electronics Products</u>
 - Project 2: A Comprehensive Approach for <u>Product Circularity</u>
 <u>Assessment</u> Towards Sustainable Value Creation
 - Project 3: Developing Methods for Assessing and Improving Circularity of <u>Consumer Electronics Products and Semiconductor Chips</u>



INEMI Roadmap Industry Issues/Needs

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MAPT Roadmap Focus Areas





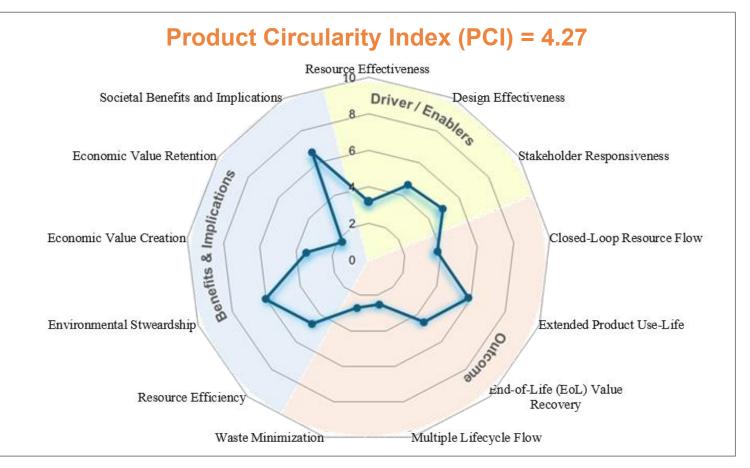






Product Circularity Index (PCI)

- Comprehensive, metricsbased method developed with extensive engagement of industry stakeholders¹
- Validated through three industry case studies



Holistic View of Overall Product Circularity Performance





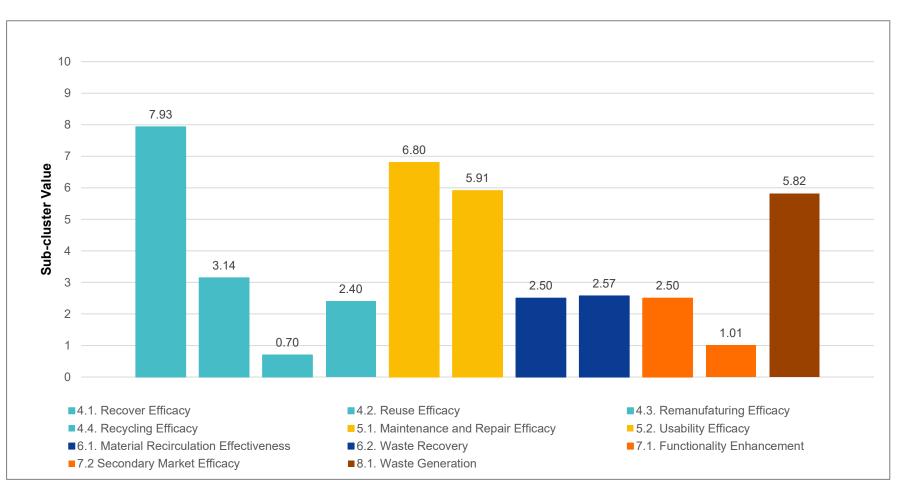


PCI Results (Contd.)

- Facilitates assessing key product features and properties to enhance product circularity¹
- Useful for making design improvement decisions – 'sustainability by design'

1) Source: Ko et al, 2025 Forthcoming

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Product Circularity Performance at Sub-cluster Level – An Example



ASTM E3461 – 25: Standard Guide for Principles of Circular Product Design



ASTM E3461-25 aims to...

- Provide guidelines and context for product designers
- Develop based on a comprehensive circular product design literature
- Support better understand, apply, and qualify design decisions



Approach:

- Main standard General considerations and design rules that are applicable to a wide set of design problems
- Appendices (in discussion) Sector-specific guidance to operationalize related Circular Design principles

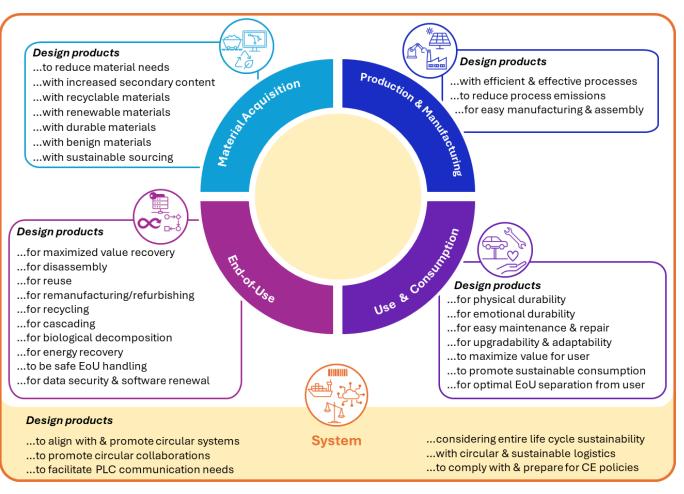
Standard drafting was a multi-stakeholder (industry, academia, government, non-profit, etc.) engaged effort



ASTEM E3461-25: Expansions Under Development

- Specific design guidance for each life cycle stage under development for ASTM balloting process
- Sector specific appendices to adapt general principles into more specific product categories such as:
 - Electronics
 - Healthcare products
 - o Textiles, etc.

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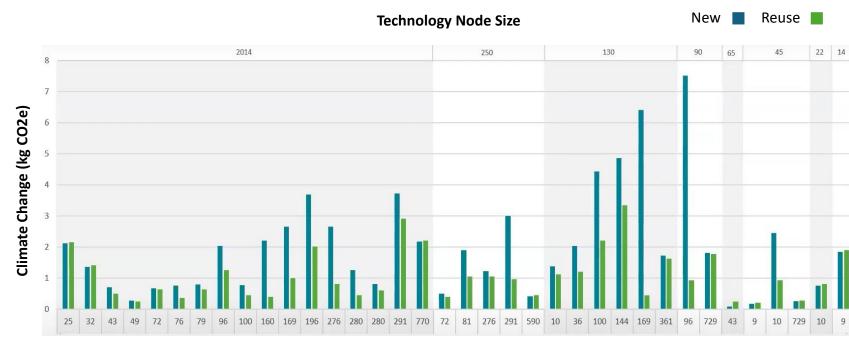


A draft list of principles based on the literature. The final list is being prepared.



Value Recovery Through Reuse of Chips

• Life cycle climate change impacts of new and reused chips¹



*Assumes 75% power for 8 hours per day, 5 days per week, over 3 years.

Die Size (mm)

EarthShift Globa



- Based on Life Cycle Assessment
- Generally lower life cycle impacts for reused chips
- New chips may have lower impacts with energy efficiency improvements



1) Ncube, A., & Stoddart, N. (2024)

Recovering Chips: Potential and Challenges

287.5B devices sold • annually in the U.S. If 1/1000 chips were reused....







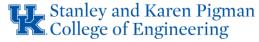
299,130 14,956,506 66,759 83.4 37,810 tons of CO2e trees growing for a cars off the road wind turbines homes powered for running for a year year a year

Positive outlook on chip reuse from industry stakeholders

Challenges identified:

- Collaboration necessary for larger scale adoption Ο
- Limited understanding of the current state of value recovery practices and perceptions Ο
- Application-specific chip design Ο
- Complexities in extracting chips without damage Ο

1) Ncube, A., & Stoddart, N. (2024)



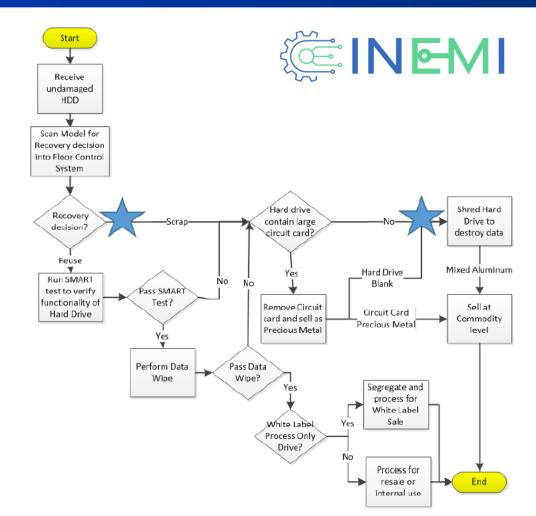


Workflows for EoL Value Recovery Strategies

- EoL recovery of chip-integrated components to enhance circularity
 - Focus group meetings with companies (ongoing) → Approaches/challenges to EoL value recovery



- Develop workflows for feasible EoL value recovery strategies
 - Identify potential for reuse or remanufacturing
 - Pilot studies to establish workflows
 - Engage the industrial community for feedback



Workflow for Hard Disk Drive Value Recovery¹



1) Handwereker et al., 2017

Concluding Remarks

- On-going efforts to address semiconductor manufacturing sustainability concerns
- Circular Economy is an enabler to advance towards sustainable value creation
 Vital for promoting sustainability in 'Semiconductor manufacturing by design'
- Design for circularity key to facilitate higher EoL value recovery
- Imperative to understand challenges to implementing circular strategies
- Tools and technologies can facilitate better assessing circularity, including metrics, must be identified
- Stakeholders to engage and establishing workflows to facilitate chip-integrated component circularity is also vital



Thank you!

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